

IN THE CLAIMS

Claim 1 (Currently Amended): A heat conductive silicone composition comprising

(a) 100 parts by weight of an organopolysiloxane having alkenyl groups only at both ends of a molecular chain,

(b) 200 to 3,000 parts by weight of a heat conductive filler,

(c) an organohydrogen polysiloxane component consisting of at least one organohydrogen polysiloxane having hydrogen atoms directly bonded to silicon atoms (Si-H groups) only at both ends of a molecular chain, in such an amount that 0.1 to 5 moles of Si-H groups are available per mole of alkenyl groups in component (a), and

(d) a platinum group base curing catalyst in an amount to give 0.1 to 500 ppm of platinum group element based on the weight of component (a),

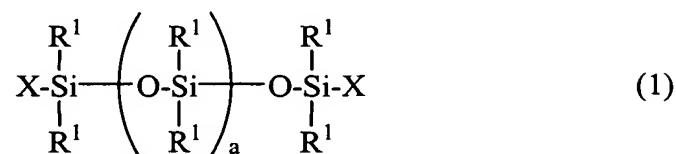
wherein the compositions when cured is non-elastic and has a penetration of 10 to 200 according to JIS K2207.

Claim 2 (Original): The composition of claim 1 wherein the heat conductive filler is selected from the group consisting of metals, oxides, nitrides, silicides, artificial diamond and mixtures thereof.

Claim 3 (Original): A heat conductive silicone article obtained by shaping the composition of claim 1 into a sheet.

Claim 4 (Original): A heat conductive silicone article shaped by applying the composition of claim 1 onto a heat dissipating sheet.

Claim 5 (Previously Presented): The composition of Claim 1, wherein the organopolysiloxane has the following formula:



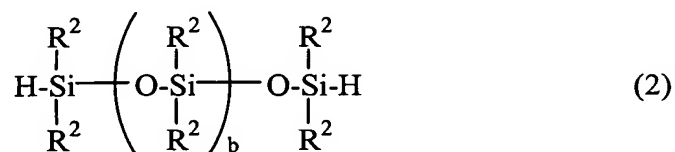
wherein R¹ is independently a substituted or unsubstituted monovalent hydrocarbon group free of aliphatic unsaturation, X is an alkenyl group, and “a” is 0 or an integer of 1 or more.

Claim 6 (Previously Presented): The composition of Claim 1, wherein the alkenyl groups are each independently selected from the group consisting of a vinyl group, an allyl group, a propenyl group, an isopropenyl group, a butynyl group, a hexenyl group, and a cyclohexenyl group.

Claim 7 (Previously Presented): The composition of Claim 1, wherein the alkenyl groups of the organopolysiloxane are vinyl groups.

Claim 8 (Previously Presented): The composition of Claim 5, wherein “a” is an integer of from 100 to 1,000.

Claim 9 (Previously Presented): The composition of Claim 1, wherein the organohydrogenpolysiloxane has the following formula:



wherein R^2 is independently a substituted or unsubstituted monovalent hydrocarbon group free of aliphatic unsaturation, and "b" is 0 or greater.

Claim 10 (Previously Presented): The composition of Claim 9, wherein R^2 is at least one of methyl, ethyl, propyl, chloromethyl, bromoethyl, 3,3,3-trifluoropropyl, cyanoethyl, phenyl, chlorophenyl and fluorophenyl.

Claim 11 (Previously Presented): The composition of Claim 9, wherein "b" is from 10 to 50.

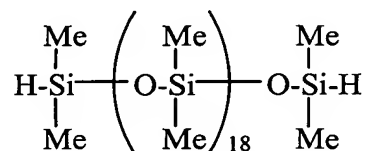
Claim 12 (Previously Presented): The composition of Claim 1, wherein the organohydrogen polysiloxane is present in an amount so that 0.5 to 2 mols of Si-H groups in the organohydrogen polysiloxane are available per mol of alkenyl groups in the organopolysiloxane.

Claim 13 (Previously Presented): The composition of Claim 1, wherein the organohydrogenpolysiloxane is present in an amount so that from 0.3 to 3 mols of Si-H groups in the organohydrogen polysiloxane are available per mol of alkenyl groups in the organopolysiloxane.

Claim 14 (Previously Presented): The composition of Claim 1, wherein the platinum group base securing catalyst is present in an amount of from 1.0 to 100 ppm based on the weight of the organopolysiloxane.

Claim 15 (Previously Presented): The composition of Claim 1, wherein the platinum group base securing catalyst is chloroplatinic acid.

Claim 16 (Previously Presented): The composition of Claim 1, comprising an organohydrogen polysiloxane of the following formula:



Claim 17 (Previously Presented): A cured composition obtained by curing the composition of Claim 1.

Claims 18-19 (Cancelled).

Claim 20 (Currently Amended): The cured composition ~~heat-conductive silicone~~ article of Claim ~~[[4]]~~ 1, ~~wherein~~ having a penetration of from 40 to 120 ~~as measured by a~~ penetrometer according to JIS K 2207.

Claim 21 (Previously Presented): The composition of Claim 1, wherein all of the organohydrogen polysiloxanes have hydrogen atoms directly bonded to silicon atoms only at both ends of a molecular chain.

BASIS FOR THE AMENDMENT

Claims 1-17 and 20-21 are active in the present application. Claim 1 has been amended to state that when cured the composition has certain non-elastic and penetration characteristics. Claims 18 and 19 are canceled claims. Support for the amendment is found in original claims 4 and previously presented Claims 18 and 20. No new matter is added.